

P-Channel Enhancement Mode MOSFET

Description

The FDN304P uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



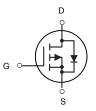
General Features

 $V_{DS} = -20V, I_{D} = -5A$

 $R_{DS(ON)}$ < 45m Ω @ V_{GS} =4.5V

Application

High power and current handing capability Lead free product is acquired Surface mount package PWM applications Load switch Power management



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
FDN304P	SOT-23	A5SHB	3000PCS

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _D s	Drain-Source Voltage	-20	V
Vgs	Gate-Source Voltage	±12	V
Ι _D	Drain Current-Continuous	-5	А
Ідм	Drain Current-Pulsed (Note 1)	-14	А
P _D	Maximum Power Dissipation	1.31	W
T _J ,T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	120	°C/W

Channel Enhancement Mode MOSE

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV_{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-20			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.014		V/°C	
		V _{GS} =-4.5V , I _D =-4.9A		35	45		
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-2.5V , I _D =-3.4A		45	60 mΩ		
		V _{GS} =-1.8V , I _D =-2A		65	85	 	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-0.4		-1.0	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-250uA		3.95		mV/°C	
	Drain-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =25°C			-1		
I _{DSS}		V _{DS} =-16V , V _{GS} =0V , T _J =55°C			-5	uA	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-3A		12.8		S	
Qg	Total Gate Charge (-4.5V)			10.2	14.3		
Q_gs	Gate-Source Charge	V_{DS} =-15V , V_{GS} =-4.5V , I_{D} =-3A		1.89	2.6	nC	
Q_{gd}	Gate-Drain Charge			3.1	4.3		
$T_{d(on)}$	Turn-On Delay Time			5.6	11.2		
Tr	Rise Time	V _{DD} =-10V , V _{GS} =-4.5V ,		40.8	73	20	
$T_{d(off)}$	Turn-Off Delay Time	R _G =3.3Ω, I _D =-3A		33.6	67	ns	
T _f	Fall Time			18	36		
C _{iss}	Input Capacitance			857	1200		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		114	160	pF	
C _{rss}	Reverse Transfer Capacitance			108	151		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}	V =V =0V Force Current			-4.9	Α
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			-14	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V
t _{rr}	Reverse Recovery Time	IF=-3A , di/dt=100A/μs ,	-	21.8		nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C		6.9		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The power dissipation is limited by 150°C junction temperature
- $\textbf{4.The data is theoretically the same as } I_D \text{ and } I_{DM} \text{ , in real applications , should be limited by total power dissipation.}$



Typical Characteristics

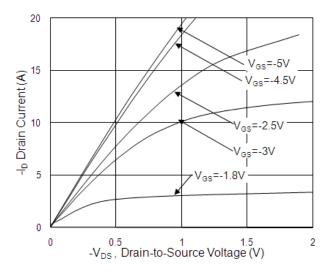


Fig.1 Typical Output Characteristics

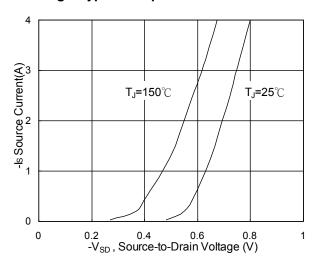


Fig.3 Forward Characteristics of Reverse

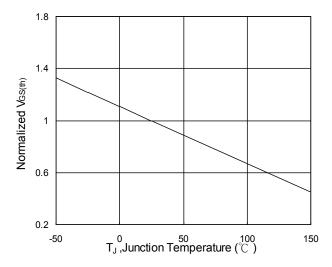


Fig.5 Normalized V_{GS(th)} vs. T_J

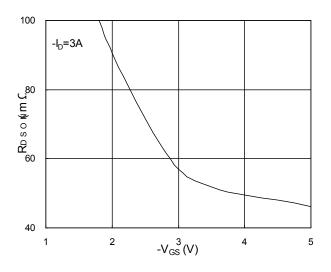


Fig.2 On-Resistance vs. G-S Voltage

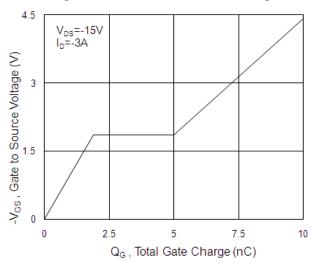


Fig.4 Gate-charge Characteristics

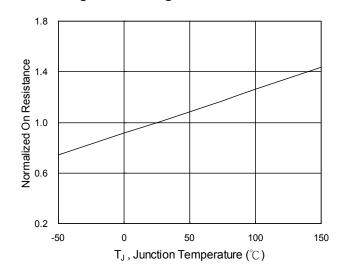
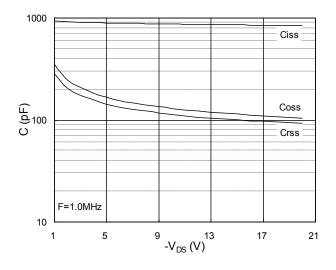


Fig.6 Normalized R_{DSON} vs. T_J



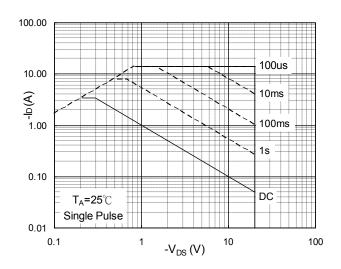


Fig.7 Capacitance

Fig.8 Safe Operating Area

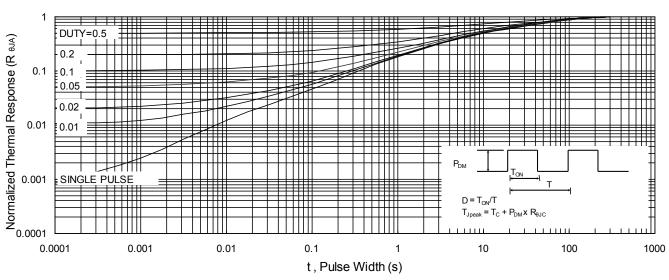
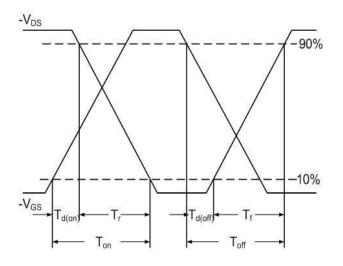


Fig.9 Normalized Maximum Transient Thermal Impedance



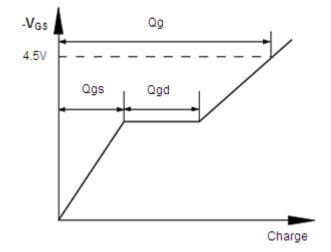
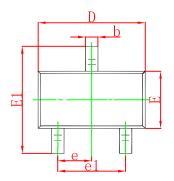


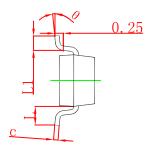
Fig.10 Switching Time Waveform

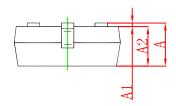
Fig.11 Gate Charge Waveform

FDN304P

SOT-23 Package Outline Dimensions

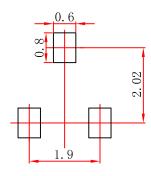






Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037	TYP	
e1	1.800	2.000	0.071	0.079	
Ĺ	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

P-Channel Enhancement Mode MOSFET

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DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7
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